Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.015”**

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**.010”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Collector**

**Mask Ref: DMB103**

**APPROVED BY: DK DIE SIZE .010” X .015” DATE: 1/26/22**

**MFG: MOTOROLA THICKNESS .006” P/N: 2N2369A**

**DG 10.1.2**

#### Rev B, 7/19/02